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Details

Product Status	Active
Core Processor	ARM® Cortex®-M23
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	17
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.63V
Data Converters	A/D 5x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	24-VFQFN Exposed Pad
Supplier Device Package	24-VQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsaml11d14a-mft

The NVM Temperature Log Row can be read at address 0x00806038.

Table 10-14. Temperature Log Row Bitfields Definition

Bit Position	Name	Description
7:0	ROOM_TEMP_VAL_INT	Integer part of room temperature in °C
11:8	ROOM_TEMP_VAL_DEC	Decimal part of room temperature
19:12	HOT_TEMP_VAL_INT	Integer part of hot temperature in °C
23:20	HOT_TEMP_VAL_DEC	Decimal part of hot temperature
31:24	ROOM_INT1V_VAL	2's complement of the internal 1V reference drift at room temperature (versus a 1.0 centered value)
39:32	HOT_INT1V_VAL	2's complement of the internal 1V reference drift at hot temperature (versus a 1.0 centered value)
51:40	ROOM_ADC_VAL	Temperature sensor 12bit ADC conversion at room temperature
63:52	HOT_ADC_VAL	Temperature sensor 12bit ADC conversion at hot temperature



Important: Hot temperature corresponds to the max operating temperature +/- 5%, so 85°C +/- 5% (package grade 'U') or 125°C +/- 5% (package grade 'F').

Table 10-15. Temperature Log Row Mapping

Offset	Bit Pos.	Name	
0x00	7:0	ROOM_TEMP_VAL_INT	
0x01	15:8	HOT_TEMP_VAL_INT	ROOM_TEMP_VAL_DEC
0x02	23:16	HOT_TEMP_VAL_DEC	HOT_TEMP_VAL_INT
0x03	31:24	ROOM_INT1V_VAL	
0x04	39:32	HOT_INT1V_VAL	
0x05	47:40	ROOM_ADC_VAL	
0x06	55:48	HOT_ADC_VAL	ROOM_ADC_VAL
0x07	63:56	HOT_ADC_VAL	

10.2.4 NVM Boot Configuration Row (BOCOR)

The Non-Volatile Memory Boot Configuration Row (BOCOR) contains device configuration data that are automatically read by the Boot ROM program at device startup.

This row can be updated using the NVMCTRL peripheral.

When writing to the NVM Boot Configuration Row, the new values are not loaded by the other peripherals on the device until a device reset occurs.

The NVM Boot Configuration Row can be read at address 0x0080C000.

SAM L10 and SAM L11 have different NVM Boot Configuration Row mappings.

10.2.4.1 SAM L10 Boot Configuration Row

Table 10-16. SAM L10 BOCOR Bitfields Definition

Bit Pos.	Name	Usage	Factory Setting	Related Peripheral Register
31:0	Reserved	Reserved	Reserved	Reserved
39:32	BOOTPROT	Boot Protection size = BOOTPROT*0x100	0x00	Boot ROM

- URWEN
- NONSECA, NONSECB, NONSECC

USERCRC is the CRC of the NVM User row area which starts from 0x00804008 and finish at 0x0080401B (bit 64 to bit 223):

Table 14-2. SAM L11 UROW Area Computed in USERCRC

Offset	Bit Pos.	Name	
0x08	71:64	AS	
0x09	79:72	Reserved	ANSC
0x0A	87:80	Reserved	DS
0x0B	95:88	Reserved	RS
0x0C	103:96	Reserved	URWEN
0x0D-0xF	127:104	Reserved	
0x10-0x13	159:128	NONSECA	
0x14-0x17	191:160	NONSECB	
0x18-0x1B	223:192	NONSECC	

14.4.2.1.2 Boot Configuration Row CRC (BOCORCRC)

BOCORCRC allows to check the following fuses parameters integrity:

- BS, BNSC
- BOOTOPT
- BOOTPROT, BCWEN, BCREN

BOCORCRC is the CRC of the NVM Boot Configuration row area, which starts from 0x0080C000 and finish at 0x00800C007 (bit 0 to bit 63).

Table 14-3. SAM L11 BOCOR Area Computed in BOCORCRC

Offset	Bit Pos.	Name	
0x00	7:0	Reserved	
0x01	15:8	BS	
0x02	23:16	Reserved	BNSC
0x03	31:24	BOOTOPT	
0x04	39:32	BOOTPROT	
0x05	47:40	Reserved	
0x06	55:48	Reserved	BCREN BCWEN
0x07	63:56	Reserved	

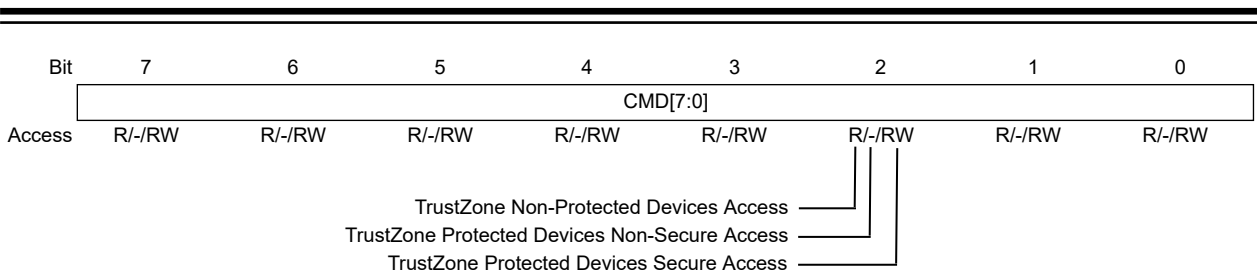
If one of the checks fails, the Boot ROM will report the error to the DSU peripheral and will enter the Boot Interactive mode:

- This will allow, if a debugger is connected, to put the device in the highest debug access level mode (DAL = 2) by issuing a Chip Erase command . Once in that mode, it is possible for a programming tool to reprogram the NVM Rows.
- When the check fails and no debugger is connected, the part will reset and restart the check sequence again.

Note: Boot Interactive mode is described later in this chapter.

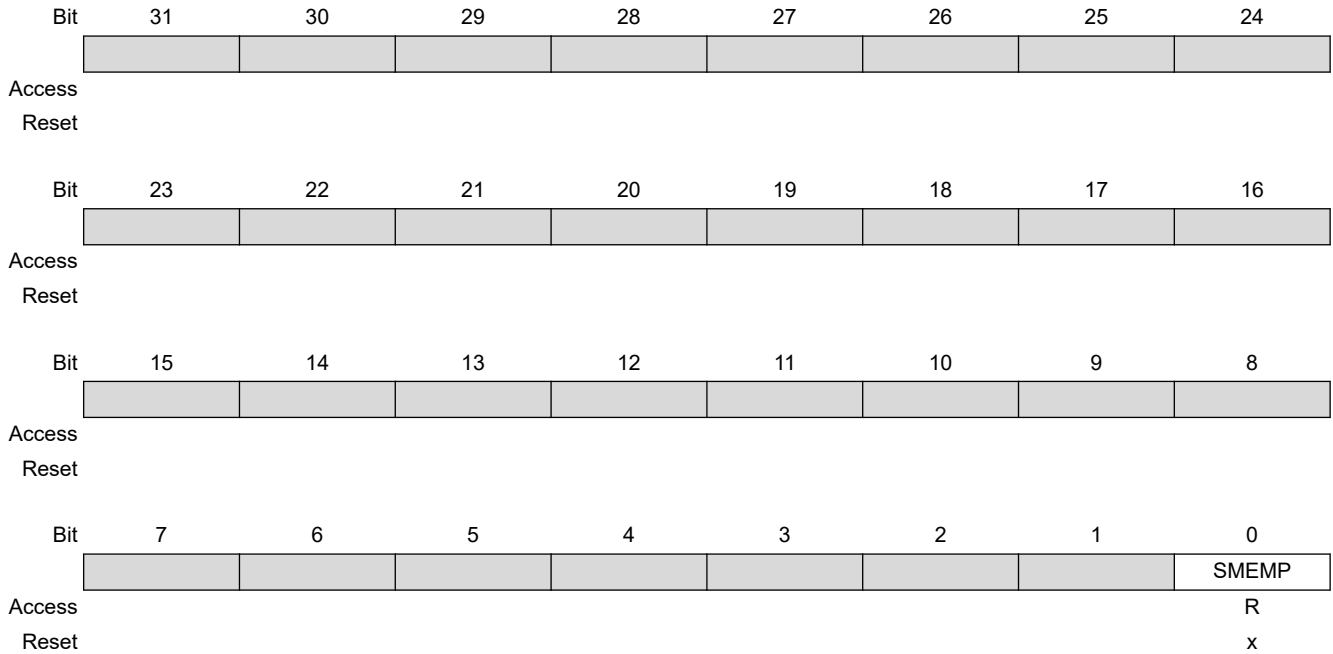
SAM L10/L11 Family

PAC - Peripheral Access Controller



16.12.16 CoreSight ROM Table Memory Type

Name: MEMTYPE
Offset: 0x1FCC
Reset: 0x0000000x
Property: -



Bit 0 – SMEMP System Memory Present

This bit indicates whether system memory is present on the bus that connects to the ROM table.

This bit is set at power-up if the device is not protected, indicating that the system memory is accessible from a debug adapter.

This bit is cleared at power-up if the device is protected, indicating that the system memory is not accessible from a debug adapter.

If the Output Enable bit in the Generator Control register is set ($GENCTRLn.OE = 1$) and the generator is enabled ($GENCTRLn.GENEN=1$), the Generator requests its clock source and the $GCLK_GEN$ clock is output to an I/O pin.

Note: The I/O pin ($GCLK/IO[n]$) must first be configured as output by writing the corresponding PORT registers.

If $GENCTRLn.OE$ is 0, the according I/O pin is set to an Output Off Value, which is selected by $GENCTRLn.OOV$: If $GENCTRLn.OOV$ is '0', the output clock will be low. If this bit is '1', the output clock will be high.

In Standby mode, if the clock is output ($GENCTRLn.OE=1$), the clock on the I/O pin is frozen to the OOV value if the Run In Standby bit of the Generic Control register ($GENCTRLn.RUNSTDBY$) is zero.

Note: With $GENCTRLn.OE=1$ and $RUNSTDBY=0$, entering the Standby mode can take longer due to a clock source dependent delay between turning off Power Domain PDSW. The maximum delay can be equal to the clock source period multiplied by the division factor.

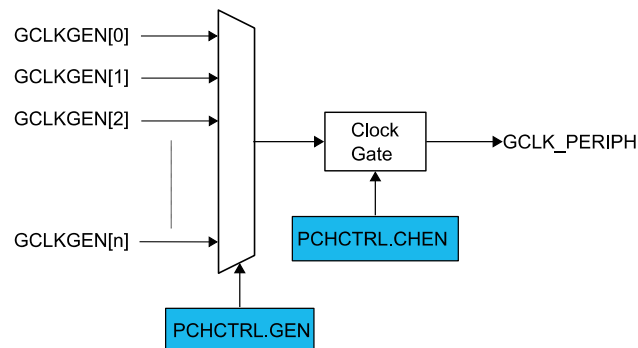
If $GENCTRLn.RUNSTDBY$ is '1', the $GCLKGEN$ clock is kept running and output to the I/O pin.

Related Links

[22.6.3.5 Power Domain Controller](#)

18.6.3 Peripheral Clock

Figure 18-4. Peripheral Clock



18.6.3.1 Enabling a Peripheral Clock

Before a Peripheral Clock is enabled, one of the Generators must be enabled ($GENCTRLn.GENEN$) and selected as source for the Peripheral Channel by setting the Generator Selection bits in the Peripheral Channel Control register ($PCHCTRL.GEN$). Any available Generator can be selected as clock source for each Peripheral Channel.

When a Generator has been selected, the peripheral clock is enabled by setting the Channel Enable bit in the Peripheral Channel Control register, $PCHCTRLm.CHEN = 1$. The $PCHCTRLm.CHEN$ bit must be synchronized to the generic clock domain. $PCHCTRLm.CHEN$ will continue to read as its previous state until the synchronization is complete.

18.6.3.2 Disabling a Peripheral Clock

A Peripheral Clock is disabled by writing $PCHCTRLm.CHEN=0$. The $PCHCTRLm.CHEN$ bit must be synchronized to the Generic Clock domain. $PCHCTRLm.CHEN$ will stay in its previous state until the synchronization is complete. The Peripheral Clock is gated when disabled.

Related Links

[18.8.4 PCHCTRLm](#)

22.7 Register Summary

Offset	Name	Bit Pos.							
0x01	SLEEPCFG	7:0						SLEEPMODE[2:0]	
0x02	PLCFG	7:0	PLDIS					PLSEL[1:0]	
0x03	PWCFCG	7:0						RAMPSWC[1:0]	
0x04	INTENCLR	7:0						PLRDY	
0x05	INTENSET	7:0						PLRDY	
0x06	INTFLAG	7:0						PLRDY	
0x07	Reserved								
0x08	STDBYCFG	7:0	VREGSMOD[1:0]			DPGPDSW			PDCFG
		15:8				BBIASSTR		BBIASHS	

22.8 Register Description

Registers can be 8, 16, or 32 bits wide. Atomic 8-, 16- and 32-bit accesses are supported. In addition, the 8-bit quarters and 16-bit halves of a 32-bit register, and the 8-bit halves of a 16-bit register can be accessed directly.

Some registers are optionally write-protected by the Peripheral Access Controller (PAC). Optional PAC write-protection is denoted by the "PAC Write-Protection" property in each individual register description. For details, refer to [22.5.7 Register Access Protection](#).

On **SAM L11** devices, this peripheral has different access permissions depending on PAC Security Attribution (Secure or Non-Secure):

- If the peripheral is configured as Non-Secure in the PAC:
 - Secure access and Non-Secure access are granted
- If the peripheral is configured as Secure in the PAC:
 - Secure access is granted
 - Non-Secure access is discarded (Write is ignored, read 0x0) and a PAC error is triggered

Refer to *Peripherals Security Attribution* for more information.

25.6.3.4 1.2V Brown-Out Detector (BOD12)

The BOD12 is calibrated in production and its calibration configuration is stored in the NVM User Row. This configuration must not be changed to assure the correct behavior of the BOD12. The BOD12 generates a reset when 1.2V crosses below the preset brown-out level. The BOD12 is always disabled in Standby Sleep mode.

25.6.3.5 Continuous Mode

Continuous mode is the default mode for BOD33.

The BOD33 is continuously monitoring the VDD supply voltage if it is enabled (BOD33.ENABLE=1) and if the BOD33 Configuration bit in the BOD33 register is cleared (BOD33.ACTCFG=0 for active mode, BOD33.STDBYCFG=0 for standby mode).

25.6.3.6 Sampling Mode

The Sampling Mode is a low-power mode where the BOD33 is being repeatedly enabled on a sampling clock's ticks. The BOD33 will monitor the supply voltage for a short period of time and then go to a low-power disabled state until the next sampling clock tick.

Sampling mode is enabled in Active mode for BOD33 by writing the ACTCFG bit (BOD33.ACTCFG=1). Sampling mode is enabled in Standby mode by writing to the STDBYCFG bit (BOD33.STBYCFG=1). The frequency of the clock ticks ($F_{clk\text{sampling}}$) is controlled by the Prescaler Select bit groups in the BOD33 register (BOD33.PSEL).

$$F_{clk\text{sampling}} = \frac{F_{clk\text{prescaler}}}{2^{(PSEL + 1)}}$$

The prescaler signal ($F_{clk\text{prescaler}}$) is a 1KHz clock, output by the 32KHz Ultra Low Power Oscillator OSCULP32K.

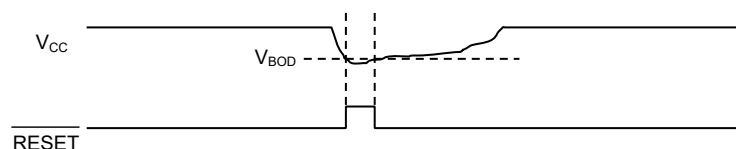
As the sampling clock is different from the APB clock domain, synchronization among the clocks is necessary. See also [25.6.6 Synchronization](#).

25.6.3.7 Hysteresis

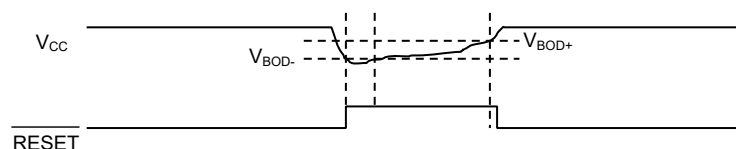
A hysteresis on the trigger threshold of a BOD will reduce the sensitivity to ripples on the monitored voltage: instead of switching $\overline{\text{RESET}}$ at each crossing of V_{BOD} , the thresholds for switching $\overline{\text{RESET}}$ on and off are separated ($V_{\text{BOD-}}$ and $V_{\text{BOD+}}$, respectively).

Figure 25-2. BOD Hysteresis Principle

Hysteresis OFF:



Hysteresis ON:

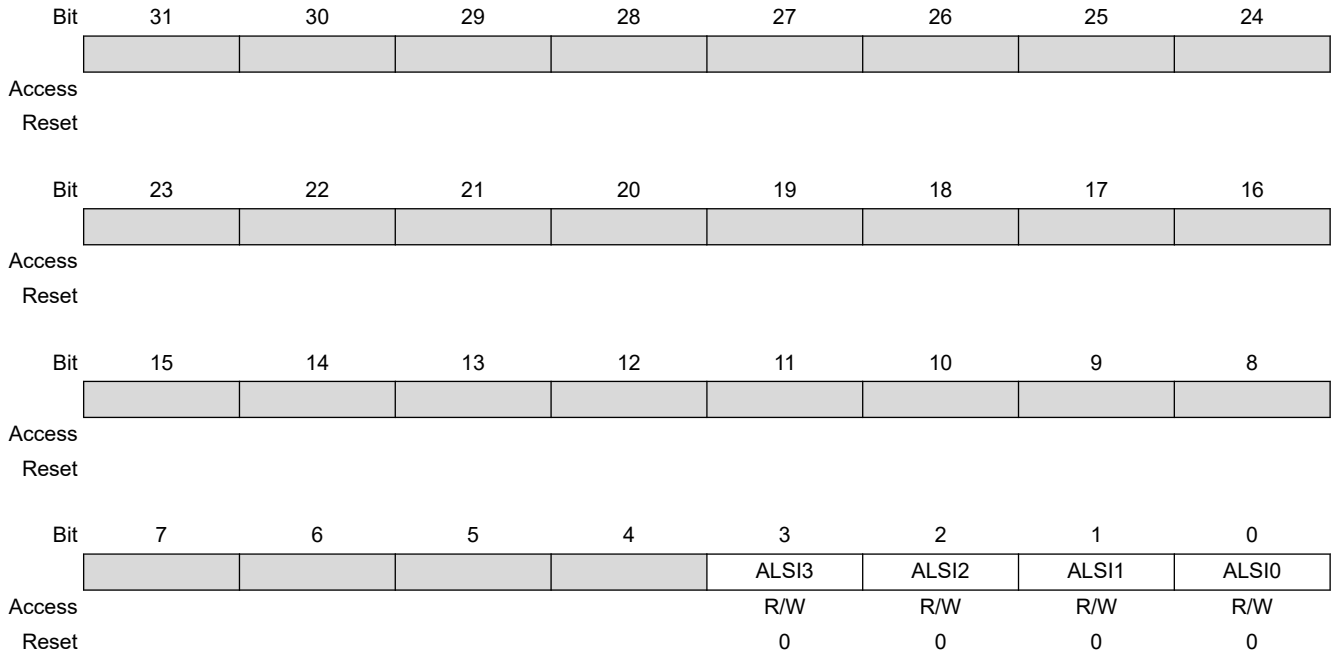


Enabling the BOD33 hysteresis by writing the Hysteresis bit in the BOD33 register (BOD33.HYST) to '1' will add hysteresis to the BOD33 threshold level.

27.6.8.4 Tamper Detection

27.10.17 Tamper Control B

Name: TAMPCTRLB
Offset: 0x6C
Reset: 0x00000000
Property: PAC Write-Protection, Enable-Protected



Bits 0, 1, 2, 3 – ALSI Active Layer Internal Select n

Value	Description
0	Active layer Protection is monitoring the RTC signal using INn and OUTn tamper pins
1	Active layer Protection is monitoring the RTC signal on the TrustRAM shield

28.8.1 Control

Name: CTRL
Offset: 0x00
Reset: 0x00X0
Property: PAC Write-Protection, Enable-Protected

	Bit	15	14	13	12	11	10	9	8
						LVLENx3	LVLENx2	LVLENx1	LVLENx0
Access						R/W	R/W	R/W	R/W
Reset						0	0	0	0
	Bit	7	6	5	4	3	2	1	0
							CRCENABLE	DMAENABLE	SWRST
Access							R/W	R/W	R/W
Reset							0	0	0

Bits 8, 9, 10, 11 – LVLENx Priority Level x Enable

When this bit is set, all requests with the corresponding level will be fed into the arbiter block. When cleared, all requests with the corresponding level will be ignored.

For details on arbitration schemes, refer to the [Arbitration](#) section.

These bits are not enable-protected.

Value	Description
0	Transfer requests for Priority level x will not be handled.
1	Transfer requests for Priority level x will be handled.

Bit 2 – CRCENABLE CRC Enable

Writing a '0' to this bit will disable the CRC calculation when the CRC Status Busy flag is cleared (CRCSTATUS.CRCBUSY). The bit is zero when the CRC is disabled.

Writing a '1' to this bit will enable the CRC calculation.

Value	Description
0	The CRC calculation is disabled.
1	The CRC calculation is enabled.

Bit 1 – DMAENABLE DMA Enable

Setting this bit will enable the DMA module.

Writing a '0' to this bit will disable the DMA module. When writing a '0' during an ongoing transfer, the bit will not be cleared until the internal data transfer buffer is empty and the DMA transfer is aborted. The internal data transfer buffer will be empty once the ongoing burst transfer is completed.

This bit is not enable-protected.

Value	Description
0	The peripheral is disabled.
1	The peripheral is enabled.

- External interrupt pins (EXTINTx). See [29.6.2 Basic Operation](#).
- Non-maskable interrupt pin (NMI). See [29.6.4 Additional Features](#).
- Non-secure check interrupt pin (NSCHK). See [29.8.8 INTFLAG](#)

Each interrupt source has an associated interrupt flag. The interrupt flag in the Interrupt Flag Status and Clear register (INTFLAG) is set when an interrupt condition occurs (NMIFLAG for NMI). Each interrupt, except NMI, can be individually enabled by setting the corresponding bit in the Interrupt Enable Set register (INTENSET=1), and disabled by setting the corresponding bit in the Interrupt Enable Clear register (INTENCLR=1).

An interrupt request is generated when the interrupt flag is set and the corresponding interrupt is enabled. The interrupt request remains active until the interrupt flag is cleared, the interrupt is disabled, or the EIC is reset. See the INTFLAG register for details on how to clear interrupt flags. The EIC has at least one common interrupt request line for all the interrupt sources, and one interrupt request line for the NMI. The user must read the INTFLAG (or NMIFLAG) register to determine which interrupt condition is present.

Note: Interrupts must be globally enabled for interrupt requests to be generated.

29.6.7 Events

The EIC can generate the following output events:

- External event from pin (EXTINTx).

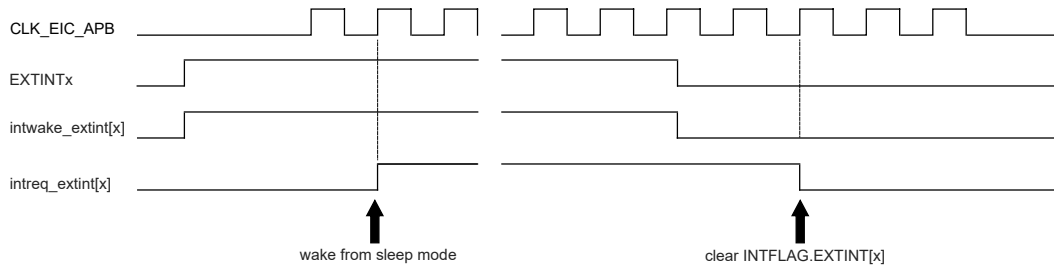
Setting an Event Output Control register (EVCTRL.EXTINTEO) enables the corresponding output event. Clearing this bit disables the corresponding output event. Refer to *Event System* for details on configuring the Event System.

When the condition on pin EXTINTx matches the configuration in the CONFIGn register, the corresponding event is generated, if enabled.

29.6.8 Sleep Mode Operation

In sleep modes, an EXTINTx pin can wake up the device if the corresponding condition matches the configuration in the CONFIG register, and the corresponding bit in the Interrupt Enable Set register ([29.8.7 INTENSET](#)) is written to '1'.

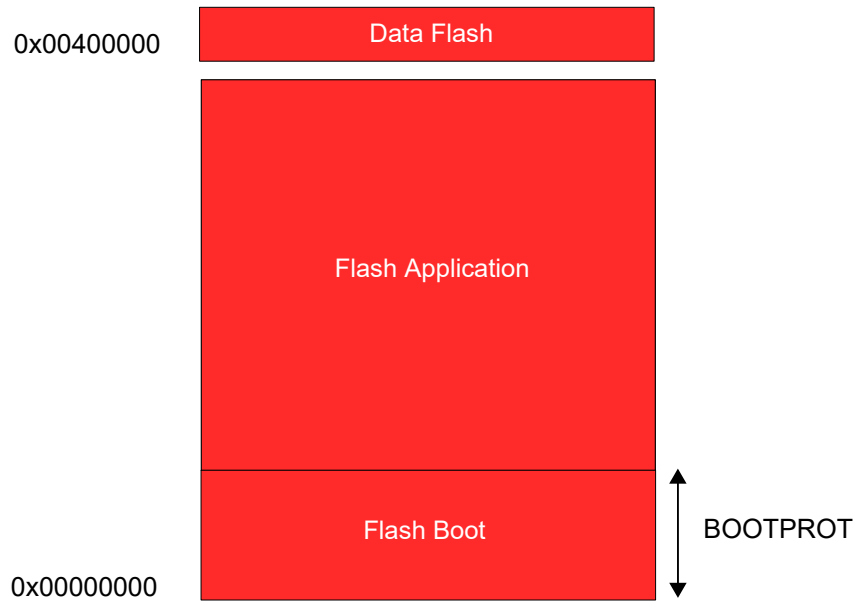
Figure 29-5. Wake-up Operation Example (High-Level Detection, No Filter, Interrupt Enable Set)



29.6.9 SAM L11 Secure Access Rights

Non-secure write to CTRLA register or DPRESALER register is prohibited. Non-secure read to CTRLA or DPRESALER register or SYNCBUSY register will return zero with no error resulting. Non-secure write to a bit of EVCTRL, ASYNCH, DEBOUNCEN, INTENCLR, INTENSET, INTFLAG and CONFIG registers is prohibited if the related bit of NONSEC.EXTINT is zero. Non-secure write to NMICTRL and NMIFLAG registers is prohibited if NONSECNMI.NMI is zero. Bits relating to secure EXTINT read as zero in non-secure mode with no error resulting.

Figure 30-3. NVM Memory Organization



The lower rows in the FLASH can be allocated as a boot loader section by using the BOOTPROT fuses. The boot loader section size is defined by the BOOTPROT fuses expressed in number of rows.



Important: Refer to the Boot ROM section to get Chip Erase commands effects for this specific BOOT area.

30.6.3 Region Unlock Bits

The NVMCTRL has the ability to lock regions defined in the NVM Memory Organization figures.

When a region is locked all modify (i.e. write or erase) commands directed to these regions are discarded. When such an operation occurs a LOCKE error is reported in the INTFLAG register and can generate an interruption.

To lock or unlock a region, write a one to the bitfield corresponding to the selected regions in the SULCK and NSULCK registers with the correct key. Writes to these registers are silently discarded when the key is not correct. Writing these registers with the correct key will temporarily lock/unlock the corresponding regions. The new setting will stay in effect until the next Reset, or until the setting is changed again while writing SULCK and NSULCK. The current status of the lock can be determined by reading the SULCK and NSULCK registers. To change the default lock/unlock setting for a region, the user row of the AUX FLASH must be written using the Write Page command. Writing to the AUX FLASH user row will take effect after the next Reset. Therefore, a boot of the device is needed for changes in the lock/unlock setting to take effect. Refer to the Physical Memory Map for calibration and auxiliary space address mapping.

30.6.4 Command and Data Interface

The NVM Controller is addressable from the APB bus, while the NVM main address space is addressable from the AHB bus. Read and automatic page write operations are performed by addressing the FLASH, Data FLASH and AUX FLASH spaces directly, while other operations such as manual page writes and row erases must be performed by issuing commands through the NVM Controller.

and can reside in program or data memory. To use this feature, the row must be previously erased and the page buffer must contain the desired data to be written.

As the Page Buffer is lost when the NVM enters low power mode (refer to [30.5.1 Power Management](#)) cannot be used if the device enters STANDBY mode or if the NVM uses power reduction modes.

The cache coherency is not ensured after an Event Automatic Write in a FLASH page. The FLASH region is cacheable, it is the user responsibility to clear the cache after such an action. Note that the Data FLASH is not subject to cache coherency issues since it is not cacheable.

30.6.7 Tamper Erase

Tamper Erase ensures rapid overwrite on tamper of a Data FLASH row selected by SECCTRL.TEROW.

When a RTC tamper event occur while tamper erase is enabled (SECCTRL.TAMPEEN=1):

- the Tamper Erase row in data space addressed by SECCTRL.TEROW is written to zero.

This is performed using a special overwrite mechanism in the NVM block that overwrites the complete row with zero. The RTC must be configured to generate the tamper erase event.

Note: Data Flash endurance is affected by the tamper erase feature. Refer to the "NVM Reliability Characteristics" from Electrical Characteristics chapter.

30.6.8 Silent Access

When enabled (SECCTRL.SILACC=1), Silent accesses are performed when accessing one Data Flash row selected by SECCTRL.TEROW. The physical and logical size of the TEROW is divided by two to store each word of Data and its complement to reduce Data Flash reading noise.

When Silent Access is enabled, data in the selected Tamper Erase ROW must be accessed using following address mapping:

TEROW_base_address

W31	W30	W29	...	W3	W2	W1	W0	Page
Data	Data	Data	Data	Data	Data	Data	Data	page0
Data	Data	Data	Data	Data	Data	Data	Data	page1
reserved	reserved	reserved	reserved	reserved	reserved	reserved	reserved	page2
reserved	reserved	reserved	reserved	reserved	reserved	reserved	reserved	page3

TEROW_base_address + ROW size

All accesses to Reserved area are discarded and generate a bus error.

Note that the physical TEROW mapping in Data Flash is the following:

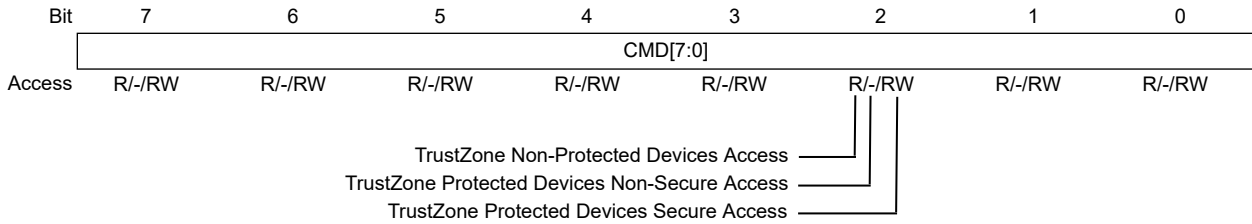
TEROW_physical_base_address

W31	W30	W29	...	W3	W2	W1	W0	Page
CompData	Data	CompData	Data	CompData	Data	CompData	Data	page0
CompData	Data	CompData	Data	CompData	Data	CompData	Data	page1

SAM L10/L11 Family

NVMCTRL – Nonvolatile Memory Controller

On SAM L11 devices, the Mix-Secure peripheral has different types of registers (Non-Secure, Secure, Write-Secure, Mix-Secure, and Write-Mix-Secure) with different access permissions for each bitfield. Refer to *Mix-Secure Peripherals* for more details. In the following register descriptions, the access permissions are specified as shown in the following figure.



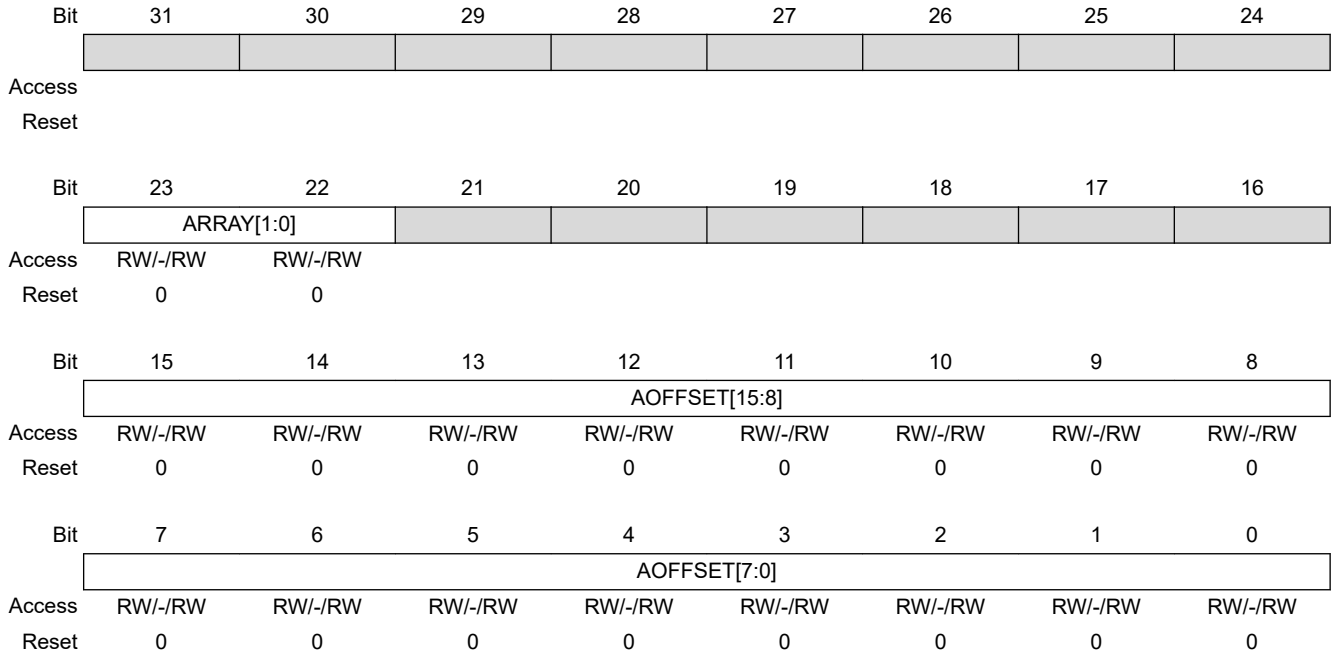
SAM L10/L11 Family

NVMCTRL – Nonvolatile Memory Controller

30.8.9 Address

Name: ADDR
Offset: 0x1C
Reset: 0x00000000
Property: PAC Write-Protection, Secure

ADDR drives the hardware address to the NVM when a command is executed using CMDEX. This is a Byte aligned address. This register is automatically updated upon AHB writes to the page buffer.



Bits 23:22 – ARRAY[1:0] Array Select

Value	Description
00	Flash
01	Data Flash
10	NVM Rows

Bits 15:0 – AOFFSET[15:0] Array Offset

Address offset

38.7.2.3 Control B Set

Name: CTRLBSET
Offset: 0x05
Reset: 0x00
Property: PAC Write-Protection, Read-synchronized, Write-Synchronized

This register allows the user to set bits in the CTRLB register without doing a read-modify-write operation. Changes in this register will also be reflected in the Control B Clear register (CTRLBCLR).

Bit	7	6	5	4	3	2	1	0
	CMD[2:0]					ONESHOT	LUPD	DIR
Access	R/W	R/W	R/W			R/W	R/W	R/W
Reset	0	0	0			0	0	0

Bits 7:5 – CMD[2:0] Command

These bits are used for software control of the TC. The commands are executed on the next prescaled GCLK_TC clock cycle. When a command has been executed, the CMD bit group will be read back as zero.

Writing 0x0 to these bits has no effect.

Writing a value different from 0x0 to these bits will issue a command for execution.

Value	Name	Description
0x0	NONE	No action
0x1	RETRIGGER	Force a start, restart or retrigger
0x2	STOP	Force a stop
0x3	UPDATE	Force update of double buffered registers
0x4	READSYNC	Force a read synchronization of COUNT

Bit 2 – ONESHOT One-Shot on Counter

This bit controls one-shot operation of the TC.

Writing a '0' to this bit has no effect.

Writing a '1' to this bit will enable one-shot operation.

Value	Description
0	The TC will wrap around and continue counting on an overflow/underflow condition.
1	The TC will wrap around and stop on the next underflow/overflow condition.

Bit 1 – LUPD Lock Update

This bit controls the update operation of the TC buffered registers.

When CTRLB.LUPD is set, no any update of the registers with value of its buffered register is performed on hardware UPDATE condition. Locking the update ensures that all buffer registers are valid before an hardware update is performed. After all the buffer registers are loaded correctly, the buffered registers can be unlocked.

Writing a '0' to this bit has no effect.

Writing a '1' to this bit will set the LUPD bit.

This bit has no effect when input capture operation is enabled.

Value	Description
0	The CCBUFx and PERBUF buffer registers value are copied into CCx and PER registers on hardware update condition.
1	The CCBUFx and PERBUF buffer registers value are not copied into CCx and PER registers on hardware update condition.

Bit 0 – DIR Counter Direction

This bit is used to change the direction of the counter.

Writing a '0' to this bit has no effect

Writing a '1' to this bit will clear the bit and make the counter count up.

Value	Description
0	The timer/counter is counting up (incrementing).
1	The timer/counter is counting down (decrementing).

41.8.2 Control B

Name: CTRLB
Offset: 0x01
Reset: 0x00
Property: PAC Write-Protection, Enable-Protected

Bit	7	6	5	4	3	2	1	0
						PRESCALER[2:0]		
Access						R/W	R/W	R/W
Reset						0	0	0

Bits 2:0 – PRESCALER[2:0] Prescaler Configuration

This field defines the ADC clock relative to the peripheral clock.

Value	Name	Description
0x0	DIV2	Peripheral clock divided by 2
0x1	DIV4	Peripheral clock divided by 4
0x2	DIV8	Peripheral clock divided by 8
0x3	DIV16	Peripheral clock divided by 16
0x4	DIV32	Peripheral clock divided by 32
0x5	DIV64	Peripheral clock divided by 64
0x6	DIV128	Peripheral clock divided by 128
0x7	DIV256	Peripheral clock divided by 256

- For this Flash technology, a maximum number of 8 consecutive writes is allowed per row. Once this number is reached, a row erase is mandatory.

Table 46-41. Flash Erase and Programming Current

Symbol	Parameter	Typ.	Units
IDD _{NVM}	Maximum current (peak) during whole programming or erase operation	10	mA

Table 46-42. NVM Reliability Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Units
Ret _{NVM25k}	Retention after up to 25k	Average ambient 55°C	10	50	Years
Ret _{NVM2.5k}	Retention after up to 2.5k	Average ambient 55°C	20	100	Years
Ret _{NVM100}	Retention after up to 100	Average ambient 55°C	25	>100	Years
Cyc _{NVM}	Cycling Endurance ⁽¹⁾	-40°C < Ta < 85°C	25K	100K	Cycles
	Cycling Endurance using Tamper Erase ⁽¹⁾	-40°C < Ta < 125°C	50	100	Cycles

Note: 1. An endurance cycle is a write and an erase operation.

46.13 Oscillators Characteristics

46.13.1 Crystal Oscillator (XOSC) Characteristics

Digital Clock Characteristics

The following table describes the characteristics for the oscillator when a digital clock is applied on XIN.

Table 46-43. Digital Clock Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units
F _{XIN}	XIN clock frequency	-	-	24	MHz
DC _{XIN} ⁽¹⁾	XIN clock duty cycle	40	50	60	%

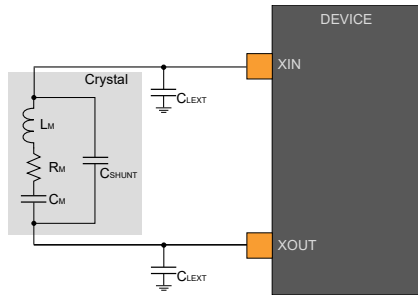
Note:

- These values are based on simulation. They are not covered by production test limits or characterization.

Crystal Oscillator Characteristics

The following Table describes the characteristics for the oscillator when a crystal is connected between XIN and XOUT.

Figure 46-3. Oscillator Connection



The user must choose a crystal oscillator where the crystal load capacitance C_L is within the range given in the Table. The exact value of C_L can be found in the crystal data sheet. The capacitance of the external capacitors (C_{LEXT}) can then be computed as follows:

$$C_{LEXT} = 2(C_L - C_{PARA} - C_{PCB} - C_{SHUNT})$$

Where:

- C_{PARA} is the internal load capacitor parasitic between XIN and XOUT ($C_{PARA} = (C_{XIN} * C_{XOUT}) / (C_{XIN} + C_{XOUT})$)
- C_{PCB} is the capacitance of the PCB
- C_{SHUNT} is the shunt capacity of the crystal.

Table 46-44. Multi Crystal Oscillator Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
Fout	Crystal oscillator frequency		0.4	-	32	MHz
ESR ⁽²⁾	Crystal Equivalent Series Resistance - SF = 3	F = 0.4MHz - CL=100 pF XOSC,GAIN=0	-	-	5.6K	Ω
		F = 2MHz - CL=20 pF XOSC,GAIN=0, Cshunt=3.3pF	-	-	330	
		F = 4MHz - CL=20 pF XOSC,GAIN=1, Cshunt=2.5pF	-	-	240	
		F = 8MHz - CL=20 pF XOSC,GAIN=2, Cshunt=5.5pF	-	-	105	
		F = 16MHz - CL=20 pF XOSC,GAIN=3, Cshunt=4pF	-	-	60	
		F = 32MHz - CL=20 pF XOSC,GAIN=4, Cshunt=3.9pF	-	-	55	
Cxin ⁽²⁾	Parasitic load capacitor		-	6.7	-	pF
Cxout ⁽²⁾			-	4.2	-	pF
Tstart ⁽²⁾	Startup time	F = 2MHz - CL=20 pF XOSC,GAIN=0, Cshunt=3.3pF	-	15.6K	81.6K	Cycles
		F = 4MHz - CL=20 pF XOSC,GAIN=1, Cshunt=2.5pF	-	6.3K	25.2K	